In The Claims:

Claim 1 (currently amended) A method of laminating copper foil onto a substrate of printed circuit board, the steps of the method comprising:

providing a substrate having an upper surface and a lower surface, wherein a circuit is formed on the surface of the substrate;

coating isolating material onto the upper surface and the lower surface of the substrate by using a rolling process;

performing a curing process to allow the isolating material to form isolating layers with a predetermined thickness on the upper surface and the lower surface of the substrate; and

after the isolating material is cured, laminating metal foils onto the isolating layers formed on the surfaces of the ~~isolating layers~~ substrate, wherein the thickness of the isolating material is determined from the type of the metal foil.

Claim 2 (original) The method of claim 1, wherein the substrate is made of flame-retardant epoxy-glass fabric composite resin (FR-4, FR-5) or bismaleimide-triazine (BT).

Claim 3 (original) The method of claim 1, wherein the isolating material comprises liquid epoxy resin.

Claim 4 (original) The method of claim 1, wherein the isolating material comprises polymer.

Claim 5 (original) The method of claim 1, wherein the isolating material comprises polyimide.

Claim 6 (canceled)

Claim 7 (original) The method of claim 1, wherein the metal foil comprises copper foil.

Claim 8 (original) The method of claim 7, wherein the types of the copper foil comprise high profile copper foil, low profile copper foil or reverse copper foil.

(claims 10-24 have been renumbered as claims 9-23, respectively.)

Claims 9 (canceled)

Claim 10 (withdrawn) The method of claim 1, wherein the step of coating the isolating material further comprises a rolling method.

Claim 11 (withdrawn) The method of claim 1, wherein the step of coating the isolating material further comprises a spraying method.

Claims 12 (canceled)

Claim 13 (currently amended) A method of laminating copper foil onto a substrate of a printed circuit board, the steps of the method comprising:

providing a substrate having an upper surface and a lower surface, wherein a circuit is formed on the surface of the substrate;

coating isolating material onto the upper surface and the lower surface of the substrate by using a rolling process;

performing a curing process to allow the isolating material to form isolating layers with a predetermined thickness on the upper surface and the lower surface of the substrate;

after the isolating material is cured, laminating metal foils onto the surfaces of the isolating layers, wherein the thickness of the isolating material is determined from the type of the metal foil; and

performing heating and pressurization processes to secure the metal foils to the surfaces of the isolating layers.

Claim 14 (original) The method of claim 13, wherein the substrate is made of flame-retardant epoxy-glass fabric composite resin (FR-4, FR-5) or bismaleimide-triazine (BT).

Claim 15 (original) The method of claim 13, wherein the isolating material comprises liquid epoxy resin.

Claim 16 (original) The method of claim 13, wherein the isolating material comprises polymer.

Claim 17 (original) The method of claim 13, wherein the isolating material comprises polyimide.

Claim 18 (original) The method of claim 13, wherein the metal foil comprises copper foil.

Claim 19 (original) The method of claim 18, wherein the types of the copper foil comprise high profile copper foil, low profile copper foil or reverse copper foil.

Claim 20 (canceled)

Claims 21 (canceled)

Claim 22 (withdrawn) The method of claim 13, wherein the step of coating the isolating material further comprises a spraying method.

Claim 23 (withdrawn) The method of claim 13, wherein the step of coating the isolating material further comprises a screen printing method.